

**Amendment to Specification**

Please replace paragraph [0011], bridging pages 5 and 6 of the specification with the following amended version thereof:

[0011] Further, in the case of the integrated optical element according to the present invention, the light emission layer of the optical semiconductor element is shifted further toward the ~~outer periphery side of the cross-section~~ silicon bench than the center of the cross-section of the optical semiconductor element that is orthogonal to the light emission layer, and the optical waveguide of the optical circuit element is also shifted further toward the outer boundary of the cross-section than the center of the cross-section of the optical circuit element that is orthogonal to the optical waveguide. Here, all of the elements are preferably arranged on the element mount surface of the silicon bench such that the distance between the silicon bench, and the light emission layer and optical waveguide is minimized. In other words, the optical semiconductor element and the optical circuit element are mounted in a flip chip state such that the light emission layer and the optical waveguide are respectively located next to the element mount surface of the silicon bench. As a result, the alignment accuracy between the optical axis of the optical semiconductor element and the optical axis of the optical waveguide of the optical circuit element can be improved.